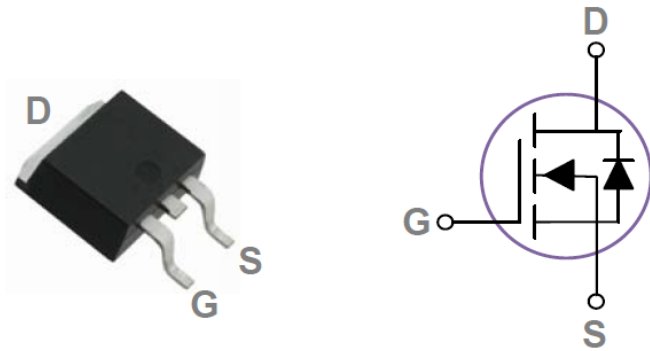


## General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

## TO252 Pin Configuration



BVDSS	RDSON	ID
100V	55mΩ	25A

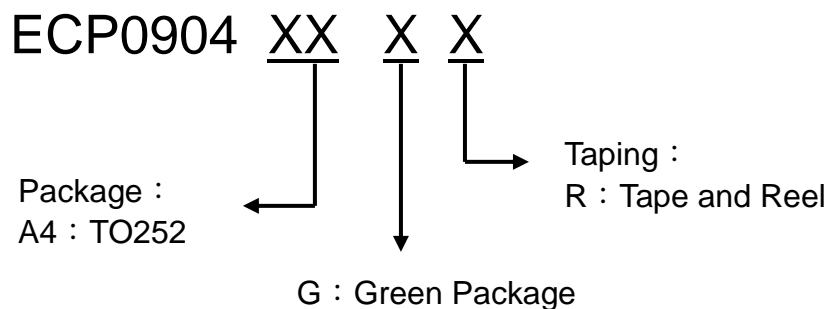
## Features

- ◆ 100V, 25A,  $R_{DS(ON)} = 55m\Omega @ V_{GS} = 10V$
- ◆ Improved dv/dt capability
- ◆ Fast switching
- ◆ 100% EAS Guaranteed
- ◆ Green Device Available

## Application

- ◆ Networking
- ◆ Load Switch
- ◆ LED applications

## Ordering Information





**Absolute Maximum Ratings**  $T_C=25^{\circ}\text{C}$  unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_C=25^{\circ}\text{C}$ )	25	A
	Drain Current – Continuous ( $T_C=100^{\circ}\text{C}$ )	15	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	100	A
$P_D$	Power Dissipation ( $T_C=25^{\circ}\text{C}$ )	73.5	W
	Power Dissipation – Derate above $25^{\circ}\text{C}$	0.58	W/ $^{\circ}\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^{\circ}\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^{\circ}\text{C}$

**Thermal Characteristics**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	1.7	$^{\circ}\text{C}/\text{W}$

**Electrical Characteristics**  $T_J=25^{\circ}\text{C}$ , unless otherwise noted

**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	100	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^{\circ}\text{C}, I_D=1\text{mA}$	---	0.05	---	V/ $^{\circ}\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=100\text{V}, V_{GS}=0\text{V}, T_J=25^{\circ}\text{C}$	---	---	1	$\mu\text{A}$
		$V_{DS}=80\text{V}, V_{GS}=0\text{V}, T_J=125^{\circ}\text{C}$	---	---	10	$\mu\text{A}$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=10\text{A}$	---	45	55	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=5\text{A}$	---	50	60	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu\text{A}$	1.2	1.6	2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-5	---	$\text{mV}/^{\circ}\text{C}$
$g_{fs}$	Forward Transconductance	$V_{DS}=10\text{V}, I_D=3\text{A}$	---	8.7	---	S

**Dynamic and switching Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$Q_g$	Total Gate Charge <sup>2, 3</sup>	$V_{DS}=50\text{V}, V_{GS}=10\text{V}, I_D=5\text{A}$	---	46	80	nC
$Q_{gs}$	Gate-Source Charge <sup>2, 3</sup>		---	4.5	9	
$Q_{gd}$	Gate-Drain Charge <sup>2, 3</sup>		---	12	20	
$T_{d(on)}$	Turn-On Delay Time <sup>2, 3</sup>		---	6.8	12	
$T_r$	Rise Time <sup>2, 3</sup>	$V_{DD}=30\text{V}, V_{GS}=10\text{V}, R_G=3.3\Omega, I_D=1\text{A}$	---	21	40	ns
$T_{d(off)}$	Turn-Off Delay Time <sup>2, 3</sup>		---	32	60	
$T_f$	Fall Time <sup>2, 3</sup>		---	8.2	16	

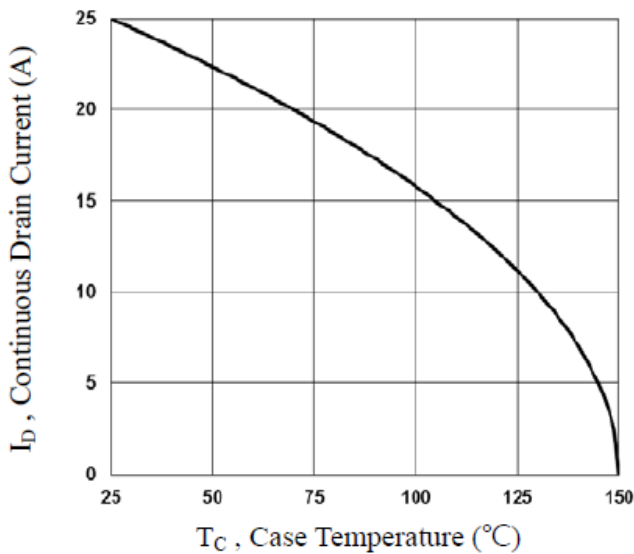
$C_{iss}$	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, F=1MHz$	---	2860	4200	pF
$C_{oss}$	Output Capacitance		---	120	180	
$C_{rss}$	Reverse Transfer Capacitance		---	70	105	
Rg	Gate resistance	$V_{GS}=0V, V_{DS}=0V, F=1MHz$	---	1.2	2.4	$\Omega$

### Drain-Source Diode Characteristics and Maximum Ratings

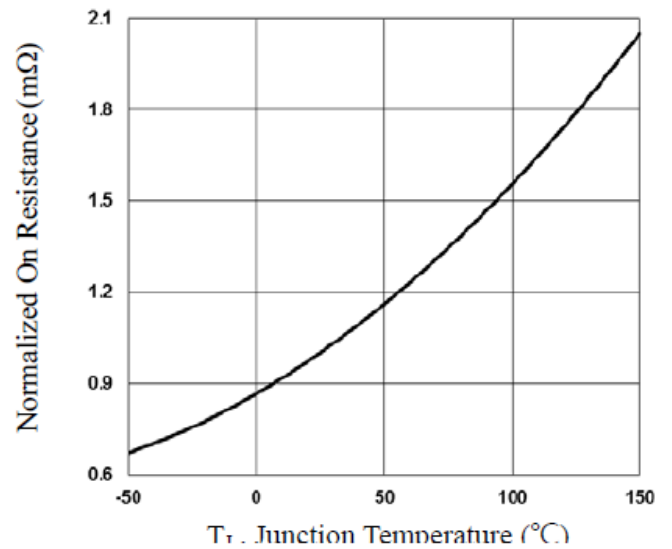
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	25	A
$I_{SM}$	Pulsed Source Current		---	---	50	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_S=1A, T_J=25^\circ C$	---	---	1	V
$t_{rr}$	Reverse Recovery Time <sup>2</sup>	$I_S=1A, di/dt=100A/\mu s$ $T_J=25^\circ C$	---	---	---	ns
$Q_{rr}$	Reverse Recovery Charge <sup>2</sup>		---	---	---	nC

Note :

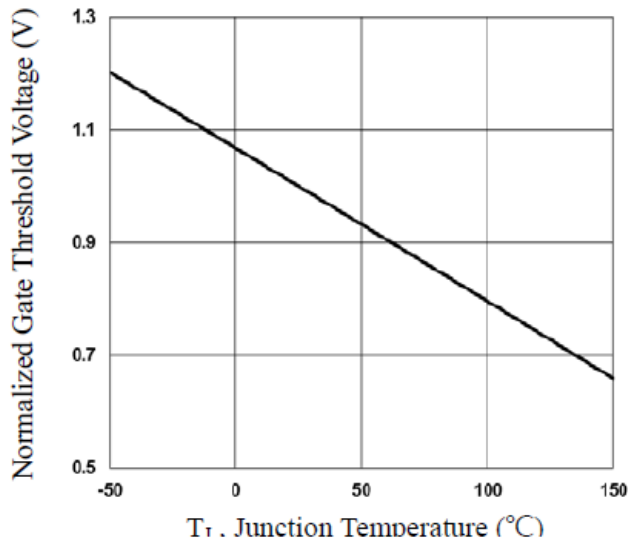
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.



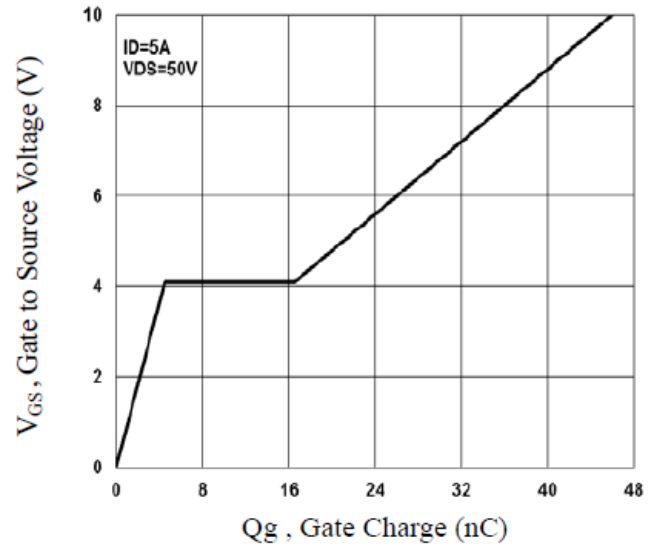
**Fig.1 Continuous Drain Current vs.  $T_C$**



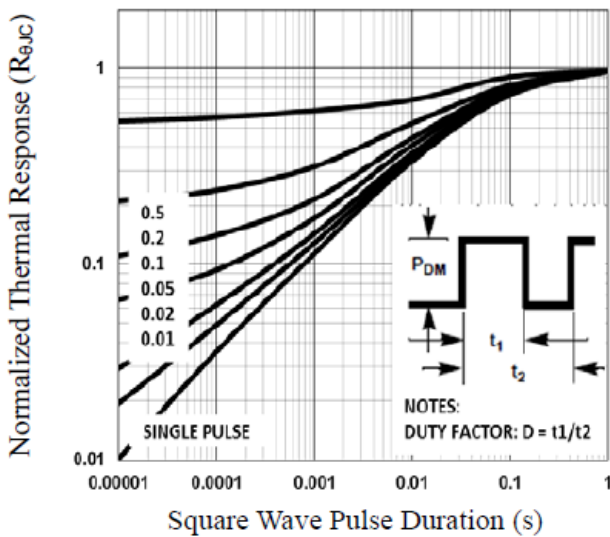
**Fig.2 Normalized  $R_{DSON}$  vs.  $T_J$**



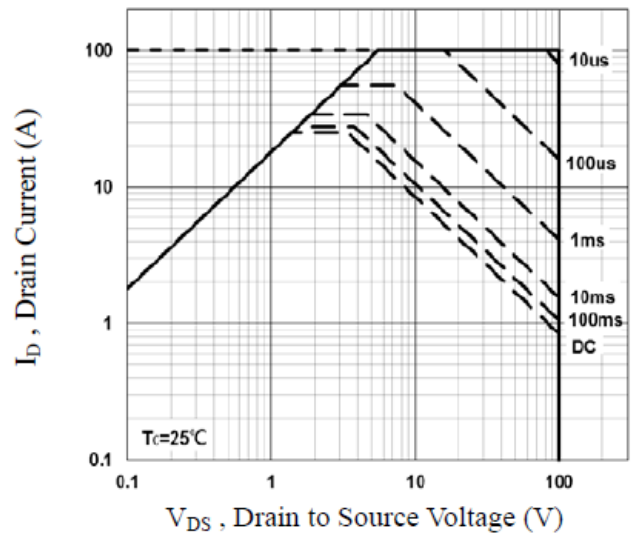
**Fig.3 Normalized Vth vs. T<sub>j</sub>**



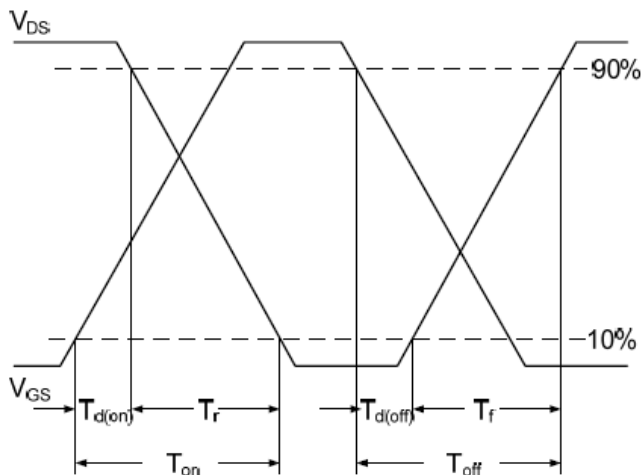
**Fig.4 Gate Charge Characteristics**



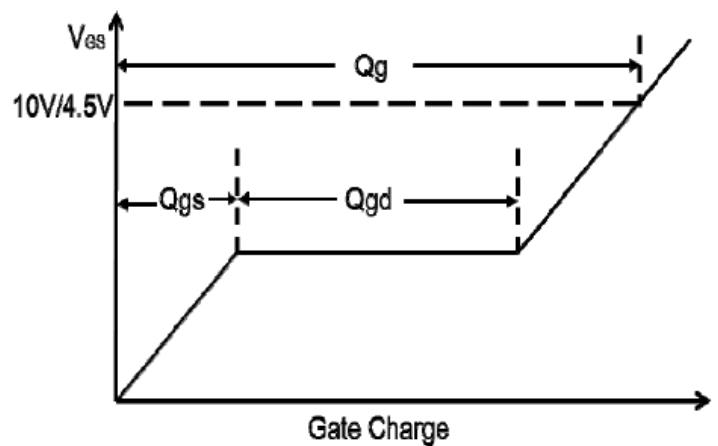
**Fig.5 Normalized Transient Impedance**



**Fig.6 Maximum Safe Operation Area**

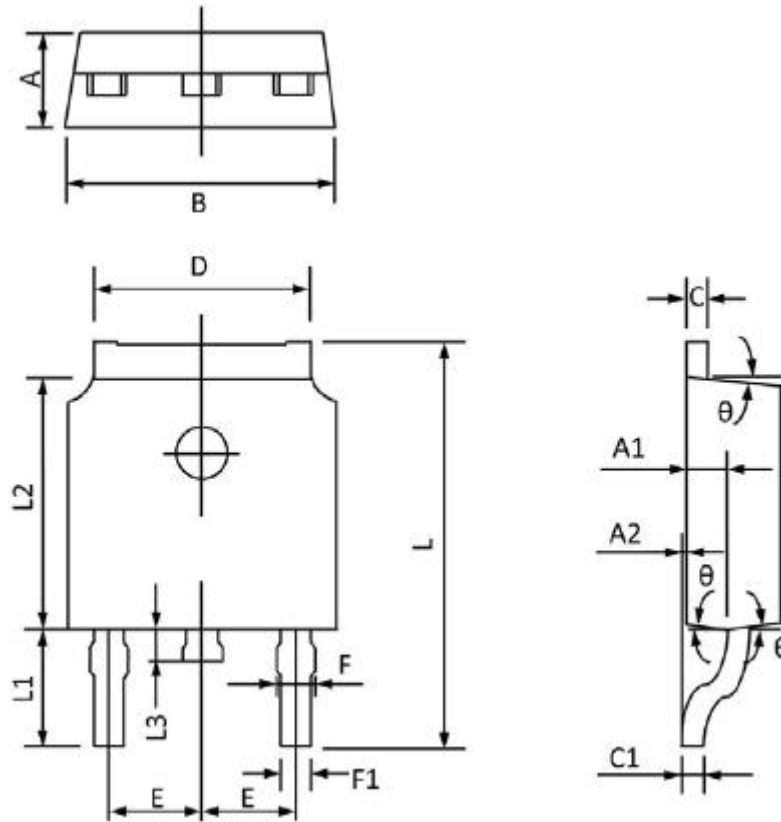


**Fig.7 Switching Time Waveform**



**Fig.8 Gate Charge Waveform**

TO252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	2.20	2.40	0.087	0.094
A1	0.91	1.11	0.036	0.044
A2	0.00	0.15	0.000	0.006
B	6.50	6.70	0.256	0.264
C	0.46	0.580	0.018	0.230
C1	0.46	0.580	0.018	0.030
D	5.10	5.46	0.201	0.215
E	2.186	2.386	0.086	0.094
F	0.74	0.94	0.029	0.037
F1	0.660	0.860	0.026	0.034
L	9.80	10.40	0.386	0.409
L1	2.9REF		0.114REF	
L2	6.00	6.20	0.236	0.244
L3	0.60	1.00	0.024	0.039
θ	3°	9°	3°	9°